

## SSC8120GS6

### **N-Channel Enhancement Mode MOSFET**

#### Features

VDS	VGS	RDSon TYP	ID	ESD	
20V	±12V	310mR@4V5		1.2K	
		490mR@2V5	1.2A		
		850mR@1V8			

#### General Description

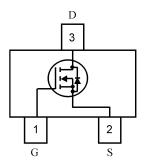
This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology .This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

#### Applications

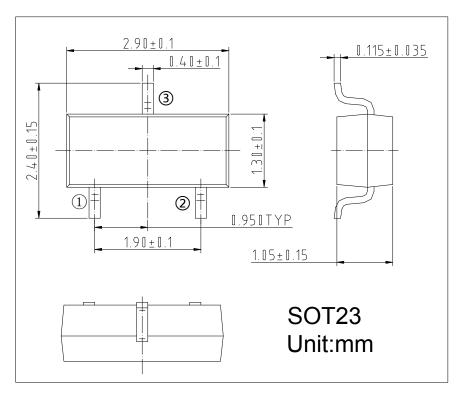
- Load Switch
- Portable Devices
- DCDC Conversion

#### Pin configuration

**Top View** 



#### Package Information





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#### • Absolute Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise noted

Parameter		Symbol	Ratings	Unit	
Drain-Source Voltage		V <sub>DSS</sub>	20	V	
Gate-Source Voltage		V <sub>GSS</sub>	±12	V	
Drain Current	Continuous	L	1.2	- A	
Drain Current	Pulsed	l <sub>D</sub>	3		
Power Dissipation <sup>(1)</sup>		P <sub>D</sub>	250	mW	
Operating and Storage Junction Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

#### ● **Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit				
OFF CHARACTERISTICS										
Drain–Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	20			V				
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0 V			1	uA				
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±12 V, V <sub>DS</sub> = 0 V			±10	uA				
ON CHARACTERISTICS <sup>(2)</sup>										
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{DS} = V_{GS}$ , $I_D = 50uA$	0.35	0.6	1	V				
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 0.6 A		310	450					
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 0.5 A		490	765	mR				
		V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 0.35 A		850	1300	1				
DYNAMIC CHARACTERISTICS										
Input Capacitance	Ciss			110		pF				
Output Capacitance	Coss	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$		15						
Reverse Transfer Capacitance	C <sub>RSS</sub>	1 - 1.0 WI 12		12						
SWITCHING CHARACTERISTICS										
Turn-On Delay Time	T <sub>D(ON)</sub>				5	nS				
Turn–On Rise Time	T <sub>R</sub>	$V_{DD} = 5 \text{ V}, I_D = 0.3\text{A},$			80					
Turn-Off Delay Tim	T <sub>D(OFF)</sub>	V <sub>GS</sub> =4.5 V,R <sub>GEN</sub> =6R			26					
Turn-Off Fall Time	T <sub>F</sub>				25					
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS										
Diode Forward Voltage <sup>(2)</sup>	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 0.11 A		0.7	1.3	V				

#### Notes:

1. Surface Mounted on FR4 Board, t < 10 sec.

Pulse Test: Pulse Width <  $300\mu s$ , Duty Cycle < 2%



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